

LED – Light Emitting Diode

Surface Mount Device

Module No.: WS2012GHC

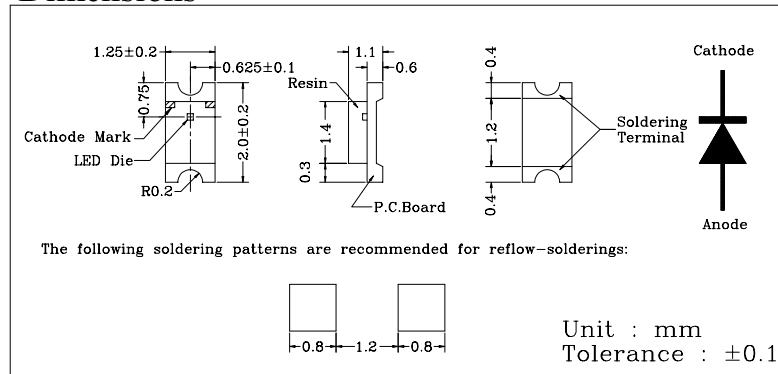
Features:

GREEN

Water Clear

High Bright

Dimensions



Absolute Maximum Ratings

(Ta=25°C)

Descriptions	Symbol	Value	Unit
Continuous Forward Current	I _F	30	mA
Peak Forward Current *1	I _{FM}	50	mA
Reverse Voltage	V _R	4	V
Operating Temperature	T _{opr}	-25 ~ +65	°C
Storage Temperature	T _{stg}	-25 ~ +85	°C
Soldering Temperature *2	T _{sol}	235	°C

*1 Duty ratio = 1/10, Pulse width = 0.1ms.

*2 Pre-heat temperature is 120~150°C for 2~3 minutes. Reflow soldering is 235±5°C within 5 seconds.

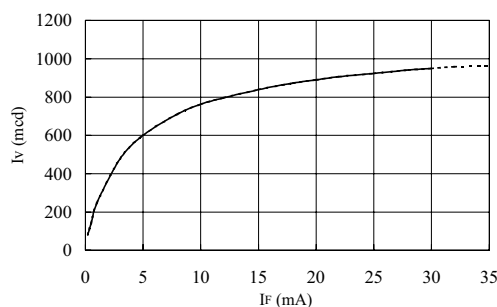
Electro-optical Characteristics

(Ta=25°C)

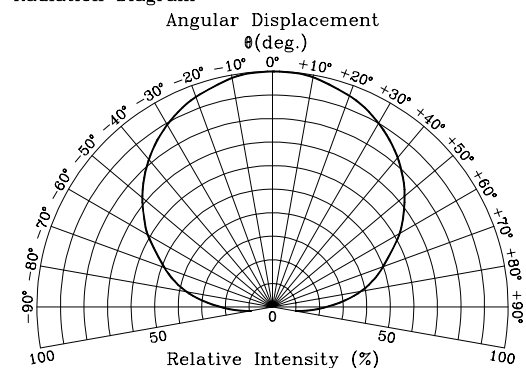
Descriptions	Symbol	Conditions	Min.	Typ.	Max.	Unit
Forward Voltage	V _{F1}	I _F =100μA	1.3			V
	V _{F2}	I _F =20mA	1.7	2.1	2.8	V
Luminous Intensity *3	I _v	I _F =20mA	530	890		mcd
Peak Emission Wavelength	λ _p	I _F =20mA		570		nm
Spectrum Radiation Bandwidth	Δλ	I _F =20mA		30		nm
Angle Sensitivity At 50%	θ			±70		deg.
Terminal Capacitance	C _t			25		pF
Response Frequency	f _c			8		MHz

*3 Tolerance: ± 30%

Luminous Intensity vs
Forward Current



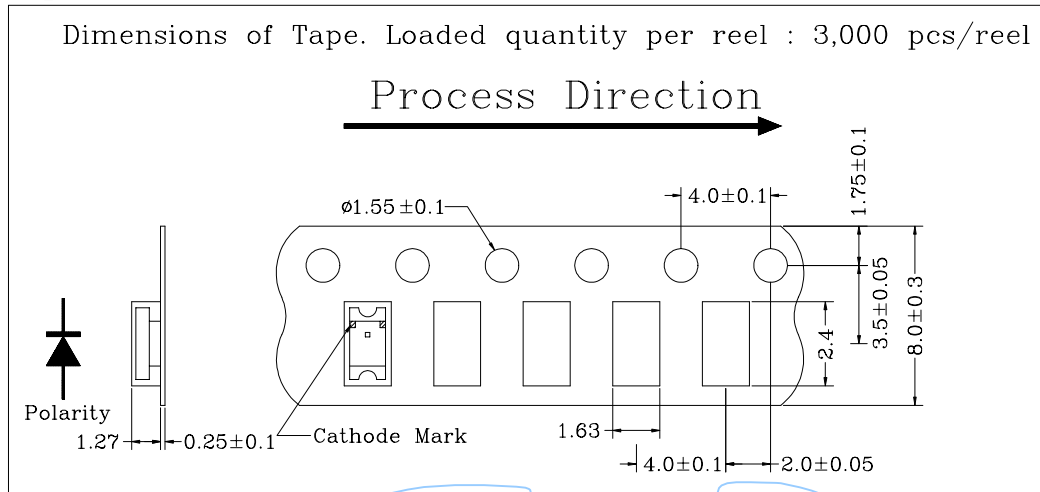
Radiation Diagram



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Tape Dimensions



Reel Dimensions

